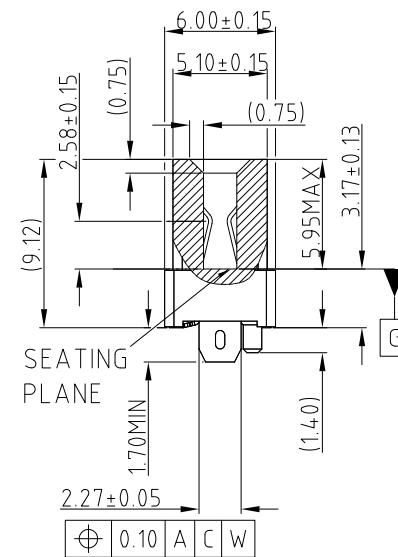
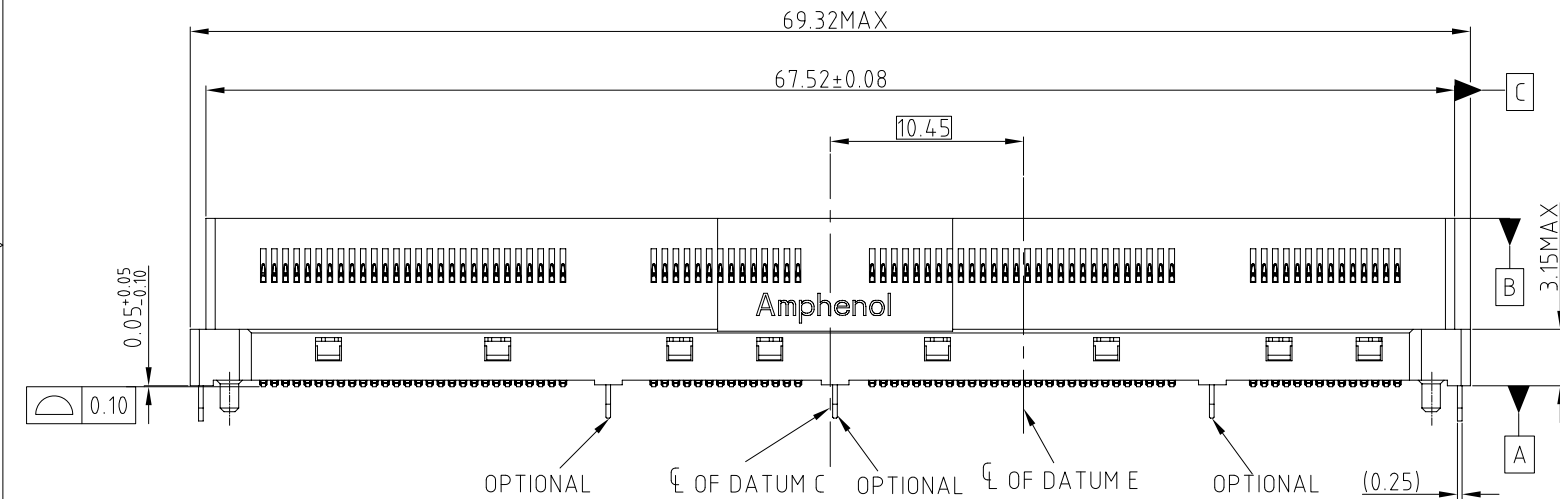
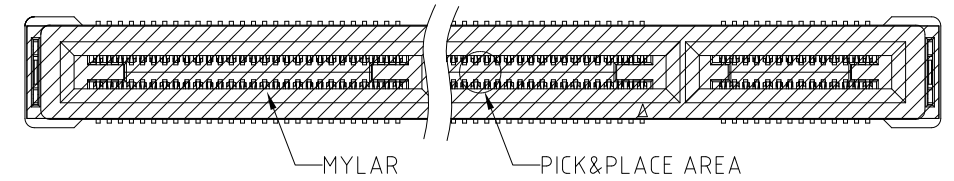
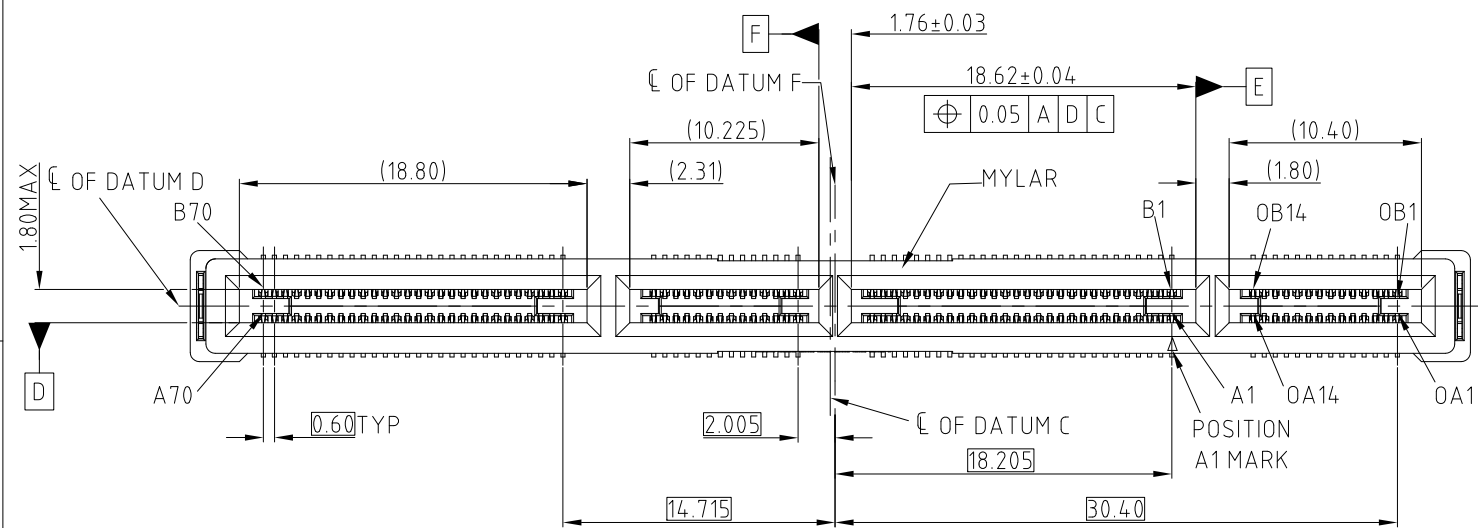


This document is the property of Amphenol Corporation and is delivered on the express condition that it is not to be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, & that no right is granted to disclose or to use any information in this document.

CUSTOMER DRAWING

REVISIONS

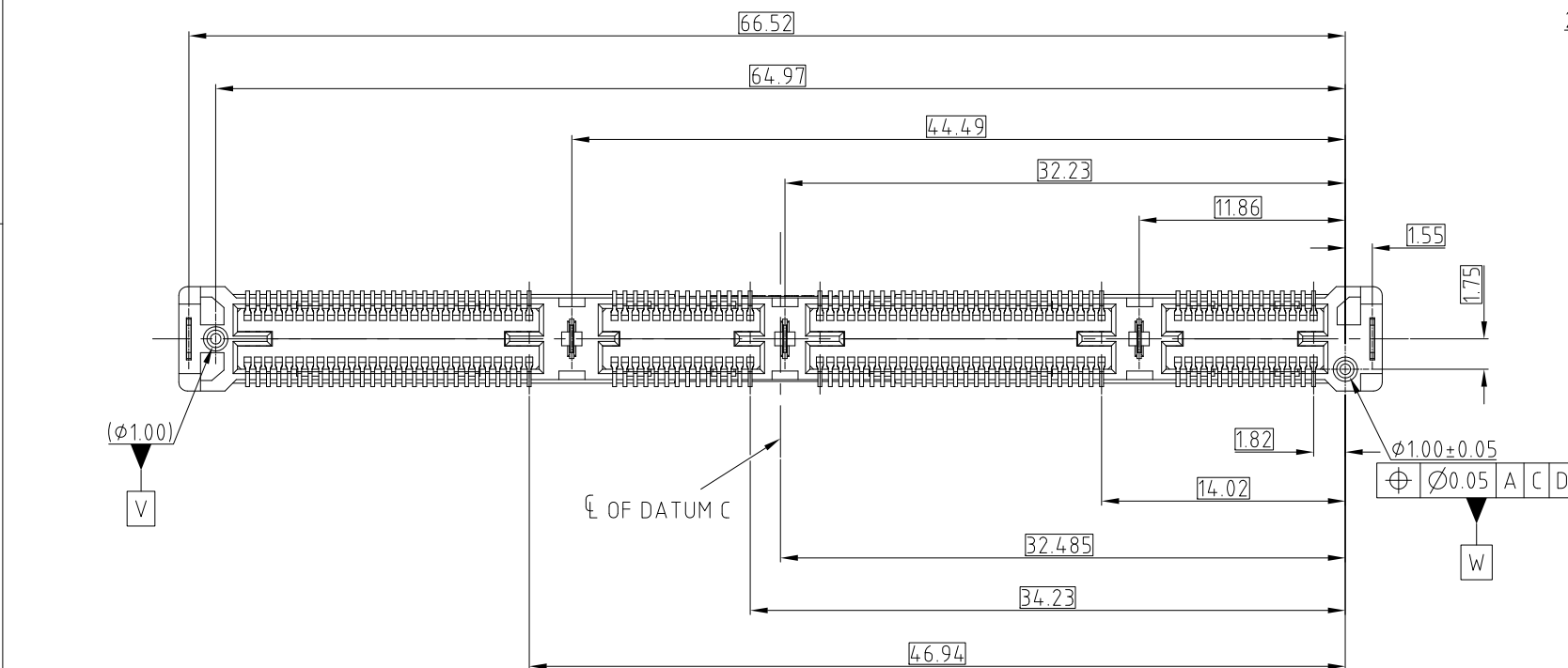
SYM	ECN	DESCRIPTION	DATE	APPROVED
1	CDXXXX	PROPOSAL DRAWING	Jul.17,2018	
2	CDXXXX	UPDATED NOTES	Jul.20,2018	
3	CDXXXX	FOLLOW SFF TA 1002 V1.1.2	Aug.20,2018	
4	CDXXXX	UPDATED BY SFF TA 1002 V1.1.3	Nov.05,2018	
5	CDXXXX	CHANGE THE CAP TO MYLAR	Dec.18,2018	



NOTE:

- MATERIAL:  
HOUSING: HIGH TEMPERATURE THERMOPLASTIC BLACK UL94-V0  
CONTACT: COPPER ALLOY  
BOARDLOCK: COPPER ALLOY
- PLATING:  
CONTACT: MATING AREA: SEE PLATING SEPC OVER 1.27-2.54 μ NICKEL UNDERPLATED  
SOLDER AREA: 1.27 MIN TIN OVER 1.27-2.54 μ NICKEL UNDERPLATED  
BOARDLOCK: 1.27 MIN TIN OVER 1.27-2.54 μ NICKEL UNDERPLATED
- ELECTRICAL PERFORMANCE:  
RATED CURRENT : 1.1A/PIN UP TO 12PINS  
LLCR:30mΩ MAX, DELTA 15 mΩ.  
INSULATION RESISTANCE: 1000MΩ MIN
- DURABILITY:200 CYCLES.
- MATERIAL SHOULD BE FULFILLED AMPHEONL SPEC# S-SN-002 AND S-SN-004
- ORDERING PN SYSTEM: ME1016810101X

- PLATING SPEC
- 0.76um Au
  - 0.38um Au
  - GOLD FLASH
  - PdNi 0.76um+GF



PROPOSAL DRAWING

UNLESS OTHERWISE SPECIFIED TOLERANCES		APPROVAL		DATE	Amphenol
U.S. METRIC		DRAWN	Rocky	Dec.18,2018	
.X	+/- 0.25	CHECKED	Ly.Yi	Dec.18,2018	
.XX	+/- 0.20	APPROVED			
.XXX	+/- 0.15	DRAWING FILE :			
FRACTIONS	+/- 5°	INTERNAL\ME\C ME101681010101X			
ANGLES	+/-	ANGLE OF PROJECTION			
FOR MATERIALS AND FINISHES SEE NOTES		REMOVE SHARP EDGES			
DIMENSIONS		SCALE			
—U.S.—	INCHES	NONE			
(METRIC)	(mm)	SHEET 1 OF 2			

TITLE		
MINI COOL EDGE CONNECTOR		
168PIN V/T 0.6MM PITCH SMT		
SIZE	DRAWING NO.	REV.
A3	C ME101681010101X	5

